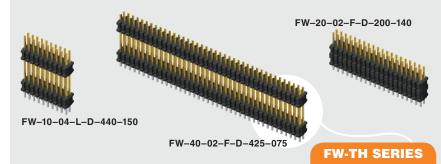




NO. PINS

LEAD



(1.27 mm) .050"

THROUGH-HOLE MICRO BOARD STACKER

SPECIFICATIONS

For complete specifications see www.samtec.com?FW-TH

Insulator Material: Black Liquid Crystal Polymer Terminal Material: Phosphor Bronze Plating:

Sn or Au over 50 μ" (1.27 μm) Ni Operating Temp Range: -55 °C to +125 °C RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

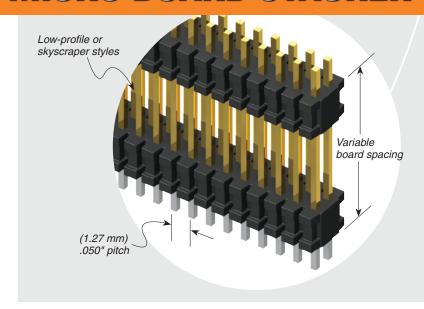


ALSO AVAILABLE (MOQ Required)

Smaller stack heights

Board Mates: CLP, FLE

Cable Mates: FFSD



STACKER

POST

OPTION

End Shroud

(-075 post height only. Mates only

with CLP.)

(5.46 mm)

.215" to

(15.49 mm)

.610"

stacker

height only,

9 pins/row

minimum

-EP

End Shroud

with Guide

Post

(-075 post

height only.

Mates only

with CLP)

(5.46 mm)

.215" to (15.49 mm)

.610" stacke

height only,

9 pins/row

minimum

HEIGHT PER ROW **HEIGHT OPTION STYLE** Specify -"XXX" "XXX" LEAD = Stacker = Post 02 thru 50 **STYLE** Height Gold flash on post, Height from (in inches) (in inches) Matte Tin on tail chart (1.65 mm) Example: .065" -250= 10 µ" (0.25 µm) = (6.35 mm)minimum Gold on post, .250" Matte Tin on tail Example: -065 No. of positions x (1.27) .050 = (1.65 mm) –G TAIL LEAD = 10 µ" (0.25 µm) 100 Gold on post, STYLE (B) Gold flash on tail (3.42)(1.14) .045 -01 .135 (4.76) .188 (1.91) .075 -02 <--(1.27) .050 (2.29) 050 -04 168 (0.41) .016 -TT TT SQ -ES **POST HEIGHT** (1.65) .065 MIN (20.32)(1.91)(3.05).800 MAX .075 DIA STACKER .120 HEIGHT (5.08) .200 MIN Į M **OVERALL** LENGTH II II В -EP (2.51)

PLATING

Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.